

**What is claimed is:**

**[Claim 1]** 1. A chip structure with bumps comprising:

a chip having an active surface and at least a bonding pad, wherein the bonding pad is formed on the active surface; and  
at least a bump disposed on the bonding pad, and the bump comprising:  
a medium layer disposed on the bonding pad, wherein a material of the medium layer includes zinc;  
a bump body disposed on the medium layer, wherein a material of the bump body includes nickel; and  
a bump body passivation layer covering the bump body except for a portion of the bump body that connects to the medium layer, wherein a material of the bump body passivation layer includes gold.

**[Claim 2]** 2. The chip structure with bumps of claim 1, wherein a height of the bump is about 5 to 10 microns.

**[Claim 3]** 3. The chip structure with bumps of claim 1, wherein a thickness of the bump body passivation layer is about 1 to 3 microns.

**[Claim 4]** 4. A bump suitable to be disposed on a chip, wherein the chip has an active surface and at least a bonding pad that exposes the active surface, and the bump comprising:

a medium layer disposed on the bonding pad; and  
a bump body disposed on the medium layer, wherein a material of the bump body includes nickel.

**[Claim 5]** 5. The bump of claim 4, further comprising a bump body passivation layer covering the bump body except for a portion of the bump body that connects to the medium layer.

**[Claim 6]** 6. The bump of claim 5, wherein a material of the bump body passivation layer includes gold.

**[Claim 7]** 7. The bump of claim 5, wherein a thickness of the bump body passivation layer is about 1 to 3 microns.

[Claim 8] 8. The bump of claim 4, wherein a height of the bump is about 5 to 10 microns.

[Claim 9] 9. The bump of claim 4, wherein a material of the medium layer includes zinc.

[Claim 10] 10. A bump suitable to be disposed on a chip, wherein the chip has an active surface and at least a bonding pad that exposes the active surface, and the bump comprising:

a medium layer disposed on the bonding pad, wherein a material of the medium layer includes zinc; and

a bump body disposed on the medium layer.

[Claim 11] 11. The bump of claim 10, further comprising a bump body passivation layer covering the bump body except for a portion of the bump body that connects to the medium layer.

[Claim 12] 12. The bump of claim 11, wherein a material of the bump body passivation layer includes gold.

[Claim 13] 13. The bump of claim 11, wherein a thickness of the bump body passivation layer is about 1 to 3 microns.

[Claim 14] 14. The bump of claim 10, wherein a height of the bump is about 5 to 10 microns.